

# Silicone Thermal Pad / XK-P80

## Introduction

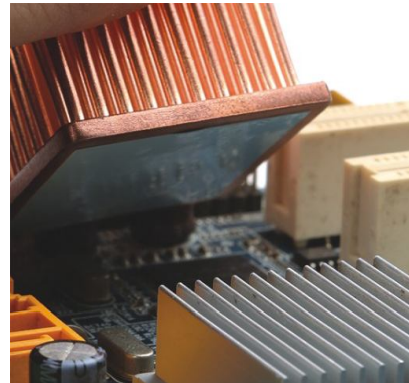
This series of products are resilient and with large deformation, suitable for large institutional design tolerances. Single or double layer structure, The Double layer is reinforced with special ultra-thin fabric to increase resistance and workability of puncture, strip type, malformation designs. Self-adhesive and never recede. No corrosion to the copper surface, "environmentally friendly products".

## Features

Ultra conformable, "gel-like" modulus  
Designed for low-stress applications  
low hardness

## Applications

Telecommunications  
Computer, Between heat-generating



	unit	XK-P80	Method
Reinforcement Carrier		-	
Inherent Surface Tack (1-/2- sided)		2-side	
Color		Dark Gray	visual
Thickness	mm	0.5-2.0	ASTM D374
Specific Gravity	g/cm <sup>3</sup>	3.55	ASTM D792
Hardness	Asker C	50	JIS K7312
	Shore 00	80	ASTM D2240
Thermal impedance@0.5mm 14.5psi	°Cin <sup>2</sup> /W	0.13	ASTM D5470
Thermal Conductivity	W/mK	8.0	HOT DISK
Volume Resistivity	Ωcm	>10 <sup>13</sup>	ASTM D257
Breakdown Voltage	KV/mm	>10	ASTM D149
Dielectric Constant	1	9	ASTM D150
Application temperature	°C	-50~200	
Tensile strength	psi	10	ASTM D149
Elongation	%	20	ASTM D149
Siloxane Volatiles D4~D20	%	<0.001	GC-FID
Flammability	UL94	V-0	UL94